

## ISL9K3060G3

### 30A, 600V Stealth™ Dual Diode

#### General Description

The ISL9K3060G3 is a Stealth™ dual diode optimized for low loss performance in high frequency hard switched applications. The Stealth™ family exhibits low reverse recovery current ( $I_{RM(REC)}$ ) and exceptionally soft recovery under typical operating conditions.

This device is intended for use as a free wheeling or boost diode in power supplies and other power switching applications. The low  $I_{RM(REC)}$  and short  $t_a$  phase reduce loss in switching transistors. The soft recovery minimizes ringing, expanding the range of conditions under which the diode may be operated without the use of additional snubber circuitry. Consider using the Stealth™ diode with an SMPS IGBT to provide the most efficient and highest power density design at lower cost.

Formerly developmental type TA49411.

#### Features

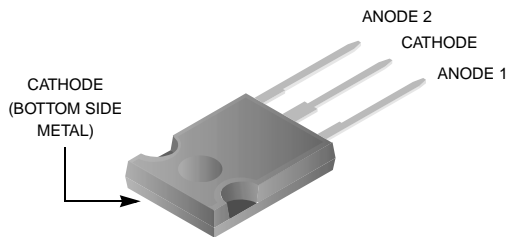
- Soft Recovery .....  $t_b / t_a > 1.2$
- Fast Recovery .....  $t_{rr} < 35ns$
- Operating Temperature ..... 175°C
- Reverse Voltage ..... 600V
- Avalanche Energy Rated

#### Applications

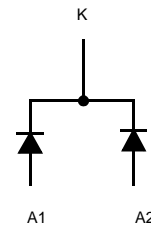
- Switch Mode Power Supplies
- Hard Switched PFC Boost Diode
- UPS Free Wheeling Diode
- Motor Drive FWD
- SMPS FWD
- Snubber Diode

#### Package

JEDEC STYLE TO-247



#### Symbol



#### Device Maximum Ratings (per leg) $T_C = 25^\circ C$ unless otherwise noted

| Symbol         | Parameter   | Ratings    | Units |
|----------------|---|------------|-------|
| $V_{RRM}$      | Repetitive Peak Reverse Voltage                           | 600        | V     |
| $V_{RWM}$      | Working Peak Reverse Voltage                              | 600        | V     |
| $V_R$          | DC Blocking Voltage                                       | 600        | V     |
| $I_{F(AV)}$    | Average Rectified Forward Current ( $T_C = 125^\circ C$ ) | 30         | A     |
|                | Total Device Current (Both Legs)                          | 60         | A     |
| $I_{FRM}$      | Repetitive Peak Surge Current (20kHz Square Wave)         | 70         | A     |
| $I_{FSM}$      | Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60Hz)  | 325        | A     |
| $P_D$          | Power Dissipation   | 200        | W     |
| $E_{AVL}$      | Avalanche Energy (1A, 40mH)                               | 20         | mJ    |
| $T_J, T_{STG}$ | Operating and Storage Temperature Range                   | -55 to 175 | °C    |
| $T_L$          | Maximum Temperature for Soldering                         |            |       |
| $T_{PKG}$      | Leads at 0.063in (1.6mm) from Case for 10s                | 300        | °C    |
|                | Package Body for 10s, See Techbrief TB334                 | 260        | °C    |

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

**Package Marking and Ordering Information**

| Device Marking | Device      | Package | Tape Width | Quantity |
|----------------|-------------|---------|------------|----------|
| K3060G3        | ISL9K3060G3 | TO-247  | -          | -        |

**Electrical Characteristics (per leg)  $T_C = 25^\circ\text{C}$  unless otherwise noted**

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|--------|-----------|-----------------|-----|-----|-----|-------|
|--------|-----------|-----------------|-----|-----|-----|-------|

**Off State Characteristics**

| Symbol | Parameter                     | Test Conditions     | $T_C = 25^\circ\text{C}$  |     |     |               |
|--------|-------------------------------|---------------------|---------------------------|-----|-----|---------------|
|        |                               |                     | Min                       | Typ | Max | Units         |
| $I_R$  | Instantaneous Reverse Current | $V_R = 600\text{V}$ | -                         | -   | 100 | $\mu\text{A}$ |
|        |                               |                     | $T_C = 125^\circ\text{C}$ |     |     |               |
|        |                               |                     | -                         | -   | 1.0 | $\text{mA}$   |

**On State Characteristics**

| Symbol | Parameter                     | Test Conditions    | $T_C = 25^\circ\text{C}$  |     |     |            |
|--------|-------------------------------|--------------------|---------------------------|-----|-----|------------|
|        |                               |                    | Min                       | Typ | Max | Units      |
| $V_F$  | Instantaneous Forward Voltage | $I_F = 30\text{A}$ | -                         | 2.1 | 2.4 | $\text{V}$ |
|        |                               |                    | $T_C = 125^\circ\text{C}$ |     |     |            |
|        |                               |                    | -                         | 1.7 | 2.1 | $\text{V}$ |

**Dynamic Characteristics**

| Symbol | Parameter            | Test Conditions                     | Min | Typ | Max | Units       |
|--------|----------------------|-------------------------------------|-----|-----|-----|-------------|
| $C_J$  | Junction Capacitance | $V_R = 10\text{V}, I_F = 0\text{A}$ | -   | 120 | -   | $\text{pF}$ |

**Switching Characteristics**

| Symbol        | Parameter                        | Test Conditions   | Min | Typ  | Max | Units                  |
|---------------|----------------------------------|---|-----|------|-----|------------------------|
| $t_{rr}$      | Reverse Recovery Time            | $I_F = 1\text{A}, di_F/dt = 100\text{A}/\mu\text{s}, V_R = 30\text{V}$  | -   | 27   | 35  | $\text{ns}$            |
|               |                                  | $I_F = 30\text{A}, di_F/dt = 100\text{A}/\mu\text{s}, V_R = 30\text{V}$   | -   | 36   | 45  | $\text{ns}$            |
| $t_{rr}$      | Reverse Recovery Time            | $I_F = 30\text{A},$<br>$di_F/dt = 200\text{A}/\mu\text{s},$<br>$V_R = 390\text{V}, T_C = 25^\circ\text{C}$        | -   | 36   | -   | $\text{ns}$            |
| $I_{RM(REC)}$ | Maximum Reverse Recovery Current |   | -   | 2.9  | -   | $\text{A}$             |
| $Q_{RR}$      | Reverse Recovered Charge         |   | -   | 55   | -   | $\text{nC}$            |
| $t_{rr}$      | Reverse Recovery Time            | $I_F = 30\text{A},$<br>$di_F/dt = 200\text{A}/\mu\text{s},$<br>$V_R = 390\text{V},$<br>$T_C = 125^\circ\text{C}$  | -   | 110  | -   | $\text{ns}$            |
| S             | Softness Factor ( $t_b/t_a$ )    |   | -   | 1.9  | -   |                        |
| $I_{RM(REC)}$ | Maximum Reverse Recovery Current |   | -   | 6    | -   | $\text{A}$             |
| $Q_{RR}$      | Reverse Recovered Charge         |   | -   | 450  | -   | $\text{nC}$            |
| $t_{rr}$      | Reverse Recovery Time            | $I_F = 30\text{A},$<br>$di_F/dt = 1000\text{A}/\mu\text{s},$<br>$V_R = 390\text{V},$<br>$T_C = 125^\circ\text{C}$ | -   | 60   | -   | $\text{ns}$            |
| S             | Softness Factor ( $t_b/t_a$ )    |   | -   | 1.25 | -   |                        |
| $I_{RM(REC)}$ | Maximum Reverse Recovery Current |   | -   | 21   | -   | $\text{A}$             |
| $Q_{RR}$      | Reverse Recovered Charge         |   | -   | 730  | -   | $\text{nC}$            |
| $di_M/dt$     | Maximum $di/dt$ during $t_b$     |   | -   | 800  | -   | $\text{A}/\mu\text{s}$ |

**Thermal Characteristics**

| Symbol          | Parameter                              | Test Conditions | Min | Typ | Max | Units                     |
|-----------------|--|-----------------|-----|-----|-----|---------------------------|
| $R_{\theta JC}$ | Thermal Resistance Junction to Case    |                 | -   | -   | 1.0 | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance Junction to Ambient | TO-247          | -   | -   | 30  | $^\circ\text{C}/\text{W}$ |

### Typical Performance Curves

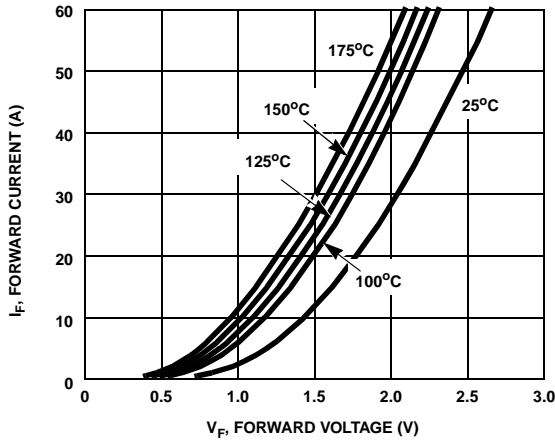


Figure 1. Forward Current vs Forward Voltage

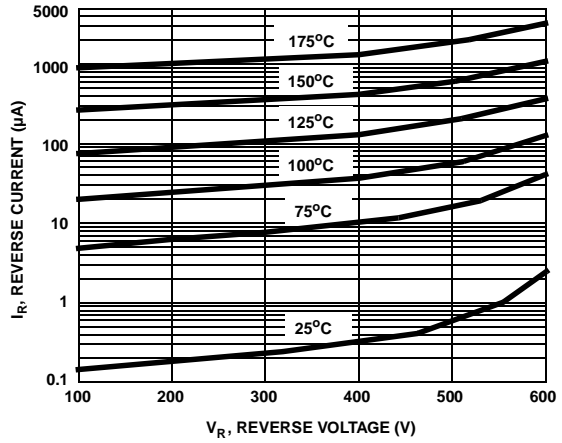


Figure 2. Reverse Current vs Reverse Voltage

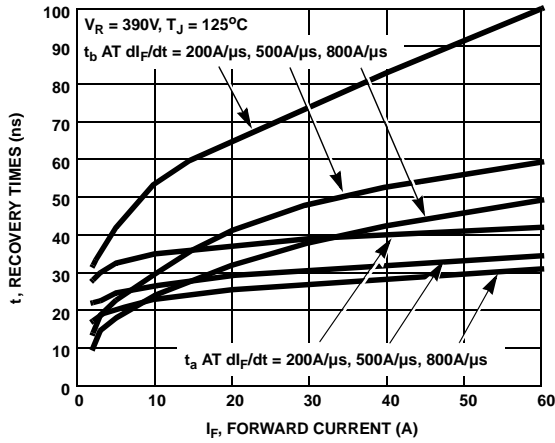


Figure 3.  $t_a$  and  $t_b$  Curves vs Forward Current

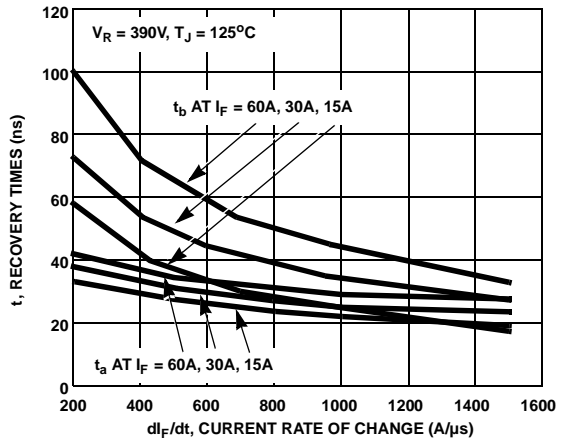


Figure 4.  $t_a$  and  $t_b$  Curves vs  $di_F/dt$

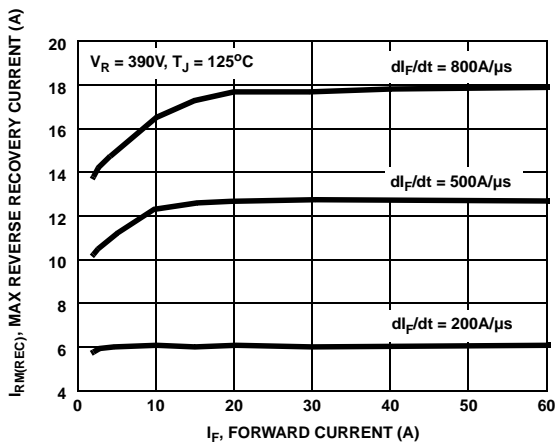


Figure 5. Maximum Reverse Recovery Current vs Forward Current

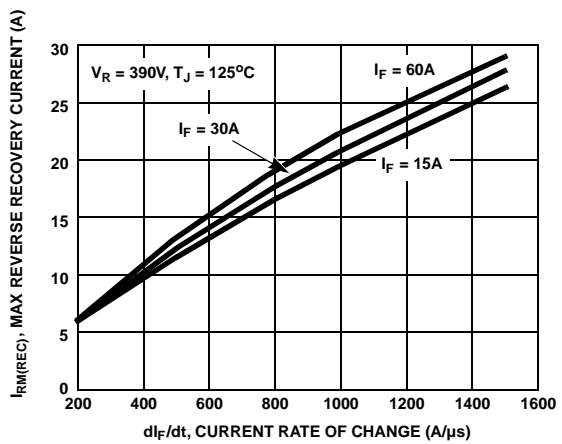


Figure 6. Maximum Reverse Recovery Current vs  $di_F/dt$

Typical Performance Curves (Continued)

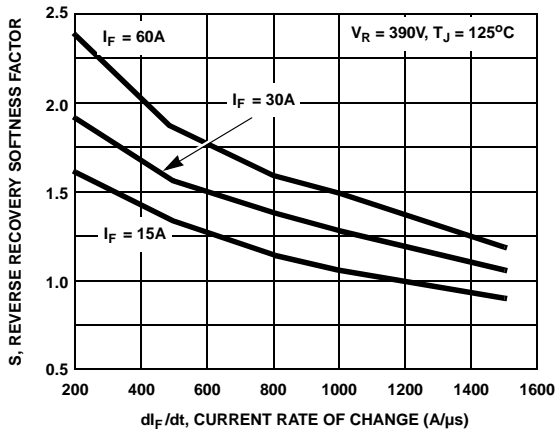


Figure 7. Reverse Recovery Softness Factor vs  $di_F/dt$

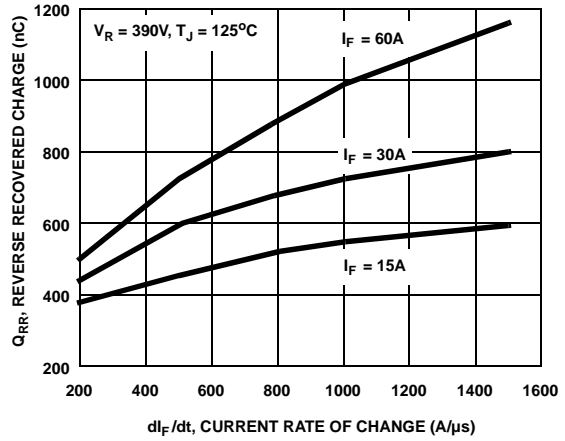


Figure 8. Reverse Recovered Charge vs  $di_F/dt$

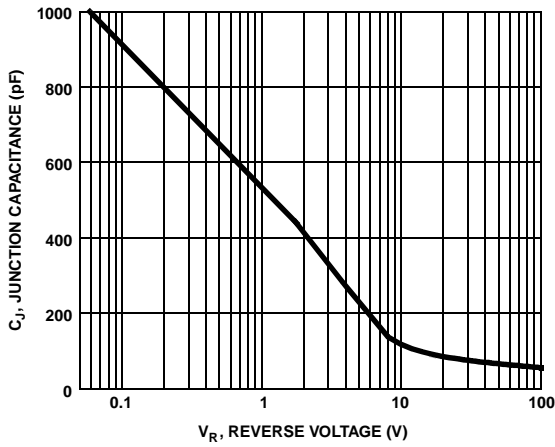


Figure 9. Junction Capacitance vs Reverse Voltage

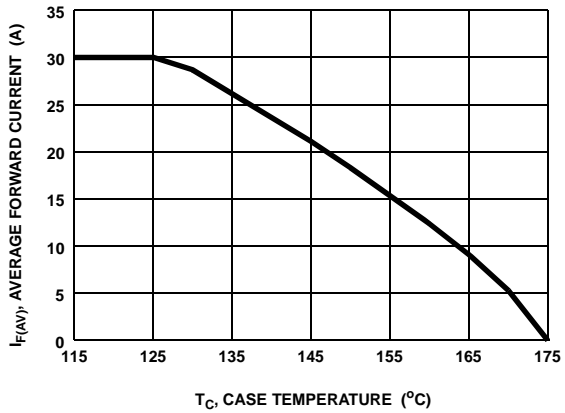


Figure 10. DC Current Derating Curve

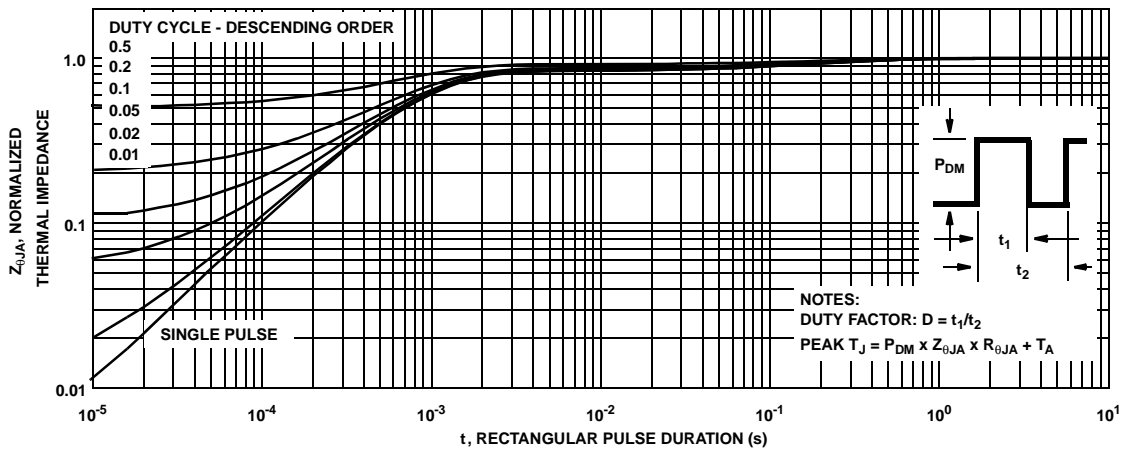


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit and Waveforms

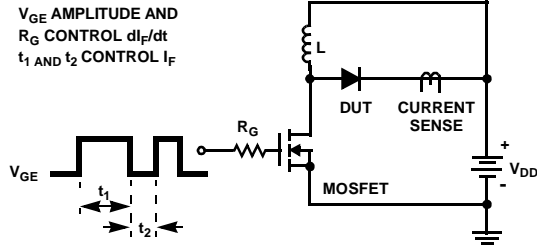


Figure 12.  $t_{rr}$  Test Circuit

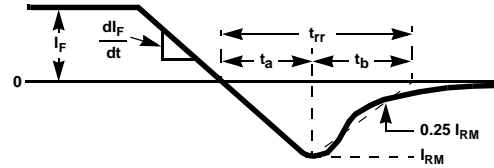


Figure 13.  $t_{rr}$  Waveforms and Definitions

$I = 1A$   
 $L = 40mH$   
 $R < 0.1\Omega$   
 $V_{DD} = 50V$   
 $E_{AVL} = 1/2LI^2 [V_{R(AVL)}/(V_{R(AVL)} - V_{DD})]$   
 $Q_1 = IGBT (BV_{CES} > DUT V_{R(AVL)})$

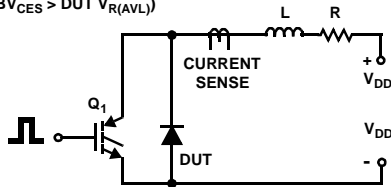


Figure 14. Avalanche Energy Test Circuit

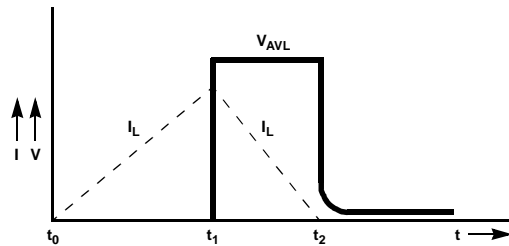


Figure 15. Avalanche Current and Voltage Waveforms

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